matching electrical path lengths and time-of-flight, impedances, and signal attenuation between different additively-manufactured electrical conduits.

21. The system of claim 1, wherein the additively-manufacture electrical conduits comprised three-dimensionally (3D) printed electrical conduits.

22. The system of claim 1, wherein the second pitch maintains a single dimension of the first pitch.

~~23. A method comprising:~~

~~generating, via an additive-manufacturing process, an interconnect comprising additively-manufactured electrical conduits that are part of an electrical pathway between electrical elements on a circuit board and contacts on a wafer, the additively-manufactured electrical conduits comprising electrically-conductive material; and~~

~~connecting the interconnect between the circuit board and the wafer;~~

~~wherein the circuit board comprises the electrical elements arranged at a first pitch; and~~

~~wherein the wafer comprises the contacts arranged at a second pitch, the second pitch being less than the first pitch.~~

~~24. The method of claim 23, wherein the at least one dielectric material comprises multiple dielectric materials.~~

~~25. The method of claim 23, where the additively-manufactured electrical conduits have a coaxial structure and wherein the at least one dielectric comprises air.~~

~~26. The method of claim 23, wherein the additively-manufactured electrical conduits comprise electrically conductive material surrounded by a dielectric, the dielectric being surrounded by a layer of electrically-conductive material.~~

~~27. The method of claim 23, further comprising:~~

~~connecting an interposer between the interconnect and the circuit board, the interposer comprising a part of the electrical pathway between the electrical elements and the contacts.~~

~~28. The method of claim 23, further comprising:~~

~~connecting electrically-conductive pins between additively-manufactured electrical conduits in the interconnect and corresponding contacts on the wafer.~~

~~29. The method of claim 23, wherein the additively-manufactured electrical conduits comprise coaxial structures.~~

~~30. The method of claim 23, wherein the circuit board further comprises:~~

~~electronics associated with each of the electrical elements, wherein electronics associated with a corresponding electrical element for supporting operation of the corresponding electrical element.~~

~~31. The method of claim 23, further comprising:~~

~~providing spring pins between the interconnect and the wafer, the spring pins for providing at least part of an electrical pathway between the contacts and the interconnect; and~~

~~connecting an interface board between the pins and the interconnect, the interface board being at least part of the electrical pathway between the contacts and the interconnect, the interface board comprising electronic components in the electrical pathway.~~

~~32. The method of claim 31, wherein the electronic components are passive electronic components.~~

~~33. The method of claim 32, wherein the electronic components comprise at least one of capacitors, baluns or switches.~~

~~34. The method of claim 31, wherein the electronic components comprise active electronic components.~~

~~35. The method of claim 23, wherein each of the electrical elements comprises part of a radio frequency (RF) probe card.~~

~~36. The method of claim 23, wherein the electrical elements comprise electrical cables that terminate on the circuit board.~~

~~37. The method of claim 23, wherein the contacts are arranged in parallel rows on the wafer; and~~

~~wherein the method further comprises:~~

~~causing a tester to make electrical contact between the interconnect and a subset of the contacts.~~

~~38. The method of claim 23, wherein at least some of the additively-manufactured electrical conduits are configured to have substantially matching electrical path lengths, impedances, and signal attenuation.~~

~~39. The method of claim 23, wherein the additively-manufactured electrical conduits comprise curved or serpentine portions configured to achieve substantially~~

~~matching electrical path lengths, impedances, and signal attenuation between different additively-manufactured electrical conduits.~~

~~40. The method of claim 23, wherein the additive-manufacturing process comprises a three-dimensional (3D) printing process.~~

~~41. The method of claim 23, wherein the additive-manufacturing process comprises a printing process in which a three-dimensional (3D) structure is created by stacking layers of material.~~

~~42. The method of claim 23, wherein the second pitch maintains a single dimension of the first pitch.~~

2343. A system comprising:

a circuit board comprising electrical elements arranged at a first pitch;

a wafer comprising contacts arranged at a second pitch, the second pitch being less than the first pitch; and

an interconnect comprising subtractively-manufactured electrical conduits that are part of an electrical pathway between the electrical elements and the contacts, the subtractively-manufactured electrical conduits comprising electrically-conductive material.

2444. The system of claim 2343, wherein the subtractively-manufactured electrical conduits have a stripline configuration, a microstrip configuration, or a co-planar waveguide configuration.

~~45. The system of claim 1, wherein the additively-manufactured electrical conduits comprise the electrically conductive material substantially surrounded by at least one dielectric material, the at least one dielectric material being substantially surrounded by a layer of electrically-conductive material.~~

~~46. The method of claim 23, wherein the additively-manufactured electrical conduits comprise the electrically conductive material substantially surrounded by at least one dielectric material, the at least one dielectric material being substantially surrounded by a layer of electrically-conductive material.~~

~~47. The method of claim 24, wherein the at least one dielectric material comprises at least one of air, ceramic and plastic.~~